

# Surface Mount Microwave Schottky Mixer Diodes

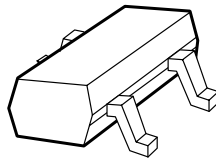
## Technical Data

**HSMS-8101 Single**  
**HSMS-8202 Series Pair**  
**HSMS-8205 Unconnected Pair**  
**HSMS-8207 Ring Quad**  
**HSMS-8209 Crossover Quad**

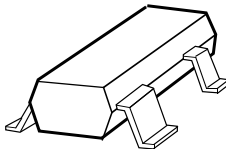
### Features

- Optimized for use at 10-14 GHz
- Low Capacitance
- Low Conversion Loss
- Low RD
- Low Cost Surface Mount Plastic Package

### Plastic SOT-23 Package



### Plastic SOT-143 Package



### Description/Applications

These low cost microwave Schottky diodes are specifically designed for use at X/Ku-bands and are ideal for DBS and VSAT downconverter applications. They are available in SOT-23 and SOT-143 standard package configurations.

Note that HP's manufacturing techniques assure that dice found in pairs and quads are taken from adjacent sites on the wafer, assuring the highest degree of match.

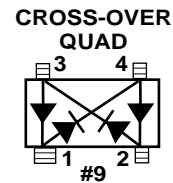
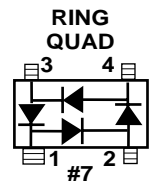
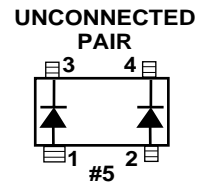
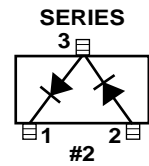
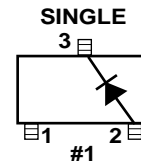
### Absolute Maximum Ratings<sup>[1]</sup>, T<sub>A</sub> = +25°C

Symbol	Parameter	Unit	Min.	Max.
P <sub>T</sub>	Total Device Dissipation <sup>[2]</sup>	mW	—	75
P <sub>IV</sub>	Peak Inverse Voltage	V	—	4
T <sub>J</sub>	Junction Temperature	°C	—	+150
T <sub>STG</sub> , T <sub>op</sub>	Storage and Operating Temperature	°C	-65	+150

### ESD WARNING:

Handling Precautions Should Be Taken To Avoid Static Discharge.

### Package Lead Code Identification (Top View)



### Notes:

1. Operation in excess of any one of these conditions may result in permanent damage to the device.
2. Measured in an infinite heat sink at T<sub>CASE</sub> = 25°C. Derate linearly to zero at 150°C per diode.

**DC Electrical Specifications,  $T_A = 25^\circ\text{C}$** 

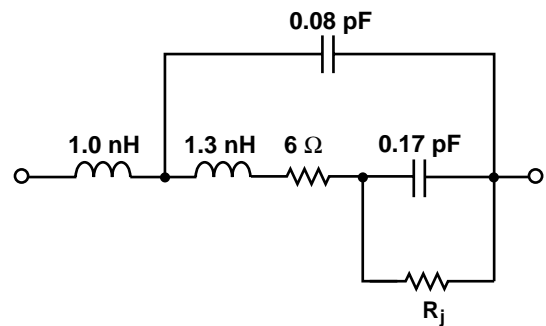
Symbol	Parameters and Test Conditions	Units	HSMS-8101		HSMS-8102		HSMS-8205		HSMS-8207		HSMS-8209	
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
$V_{BR}$	Breakdown Voltage $I_R = 10 \mu\text{A}$	V	4		4		4		4		4	
$C_T$	Total Capacitance $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	pF		0.26		0.26		0.26		0.26		0.26
$\Delta C_T$	Capacitance Difference $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	pF		—		0.04		0.04		0.04		0.04
$R_D$	Dynamic Resistance $I_F = 5 \text{ mA}$	$\Omega$		14		14		14		14		14
$\Delta R_D$	Dynamic Resistance Difference $I_F = 5 \text{ mA}$	$\Omega$		—		2		2		2		2
$V_F$	Forward Voltage $I_F = 1 \text{ mA}$	mV	250	350	250	350	250	350	250	350	250	350
$\Delta V_F$	Forward Voltage Difference $I_F = 1 \text{ mA}$	mV		—		20		20		20		20
Lead Code			1		2		5		7		9	
Package Marking Code in White			R1		2R		R5		R7		R9	

**RF Electrical Parameters,  $T_A = 25^\circ\text{C}$** 

Symbol	Parameter	Units	Typical
$L_c$	Conversion Loss at 12 GHz	dB	6.3
$Z_{IF}$	IF Impedance	$\Omega$	150
SWR	SWR at 12 GHz		1.2

**Note:**DC Load Resistance = 0  $\Omega$ ; LO Power = 1 mW.**SPICE Parameters**

$I_S = 4.6 \text{ E-}8$	$E_G = 0.69$	$TT = 0$
$R_S = 6$	$C_{JO} = 0.18 \text{ E-}12$	
$N = 1.09$	$P_B (V_J) = 0.5$	
$B_V = 7.3$	$M = 0.5$	
$I_{BV} = 10\text{E-}5$	$FC = 0.5$	

**Linear Equivalent Circuit****Self Bias**

	1 mA	2.5 mA
$R_j$	263	142

### Typical Performance, $T_c = 25^\circ\text{C}$

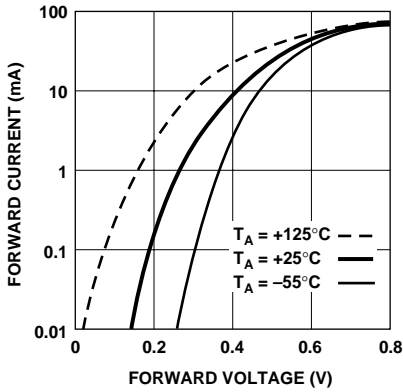


Figure 1. Typical Forward Current vs. Forward Voltage at Three Temperatures.

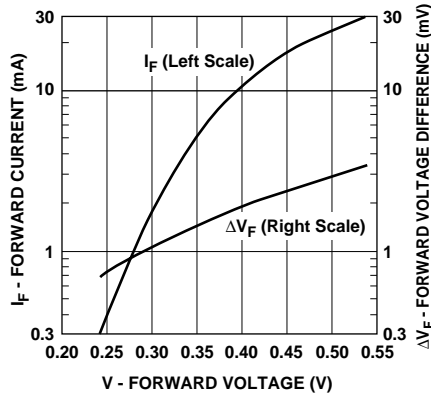


Figure 2. Typical VF Match, HSMS-820X Pairs and Quads.

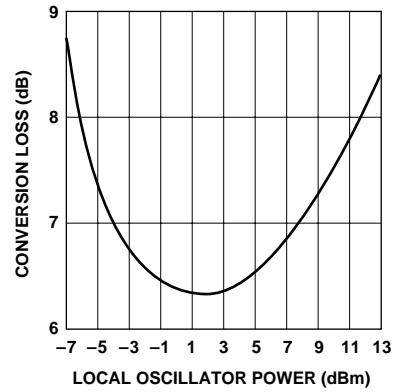
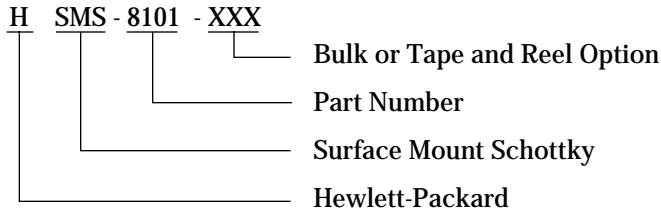


Figure 3. Typical Conversion Loss vs. Local Oscillator Power.

### Ordering Information

Specify part number followed by option. For example:



### Profile Option Descriptions

- BLK = Bulk
- TR1 = 3K pc. Tape and Reel, Device Orientation Figures 4, 5
- TR2 = 10K pc. Tape and Reel, Device Orientation Figures 4, 5

Tape and Reeling conforms to Electronic Industries RS-481, "Taping of Surface Mounted Components for Automated Placement."

### Device Orientation

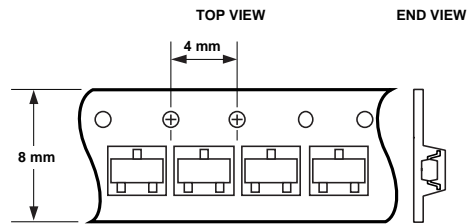
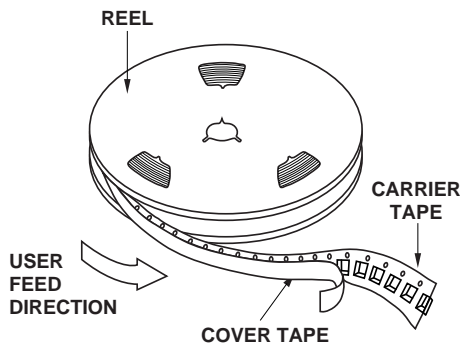


Figure 4. Option -TR1/-TR2 for SOT-23 Packages.

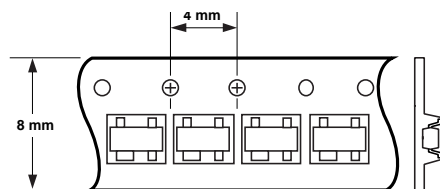
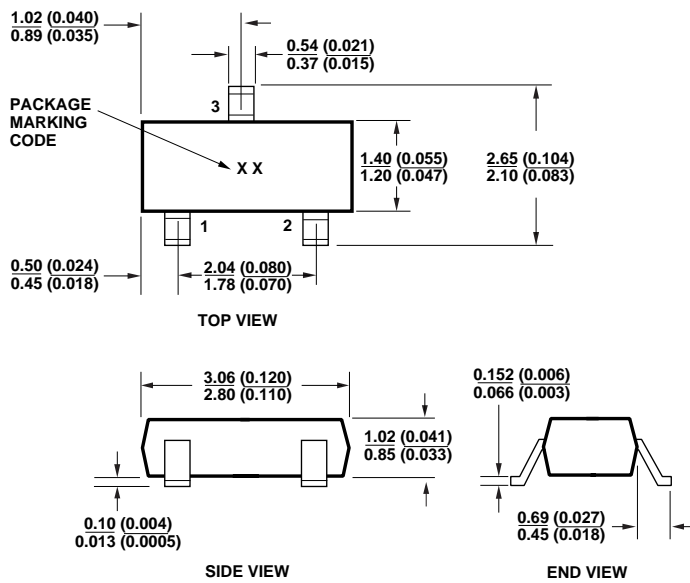


Figure 5. Option -TR1/-TR2 for SOT-143 Packages.

## Package Characteristics

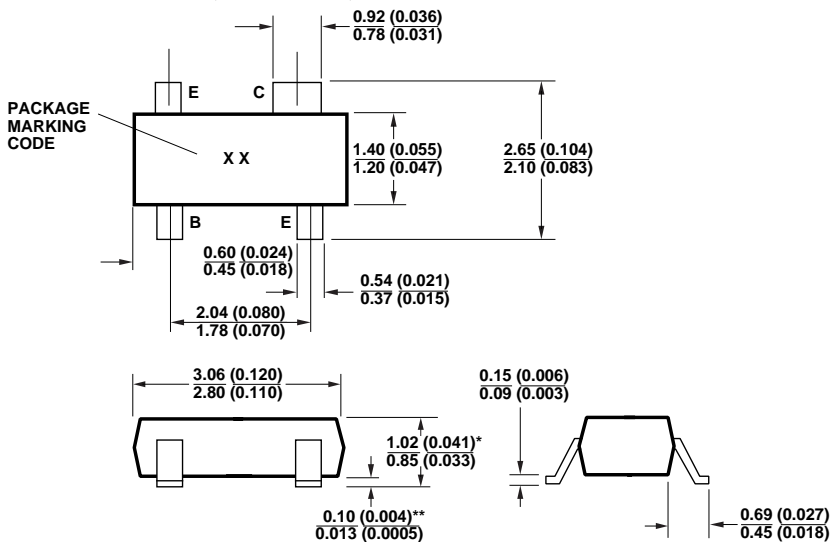
Lead Material ..... Alloy 42  
 Lead Finish ..... Tin-Lead 85-15%  
 Maximum Soldering Temperature ..... 260°C for 5 seconds  
 Minimum Lead Strength ..... 2 pounds pull  
 Typical Package Inductance ..... 2 nH  
 Typical Package Capacitance ..... 0.08 pF (opposite leads)

## Package Dimensions Outline 23 (SOT-23)



DIMENSIONS ARE IN MILLIMETERS (INCHES)

## Outline 143 (SOT-143)



DIMENSIONS ARE IN MILLIMETERS (INCHES)

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Data subject to change.  
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Obsoletes 5966-0929E

5968-3886E (3/99)